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IN THE

## UNITED STATES PATENT AND TRADEMARK OFFICE

inventor(s): David B. Miller et al.

Serial No.: 09/688,064

Examiner: Tran, Minh Loan

Filing Date: Oct. 13, 2000

Group Art Unit: 2826

Title:

ALIGNING AN OPTICAL DEVICE SYSTEM WITH AN OPTICAL LENS SYSTEM

**COMMISSIONER FOR PATENTS** Washington, D.C. 20231

## TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

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ans	smitted he	erewith is/are the f	ollowing in	n the abov	e-identified	applic	cation:				
)	Response	e/Amendment			(	) F	Petition	ı to e	extend	time to	respor
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				TOTAL A	DDITIONAL FE	E FOR	THIS A	MEN	DMENT	\$	84

84 to Deposit Account 50-1078. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 50-1078 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 50-1078 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this sheet is enclosed.

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Date of Deposit: Aug. 2, 2002

Typed Name: Edouard Garcia

Signature:

Respectfully submitted,

David B. Miller et al.

**Edouard Garcia** 

Attorney/Agent for Applicant(s)

Reg. No.

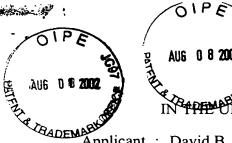
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- Attach as First Page to Transmitted Papers -



Title

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NITED STATES PATENT AND TRADEMARK OFFICE

Applicant: David B. Miller et al.

Serial No.: 09/688,064 : October 13, 2000 Filed

David B. Miller et al.

O9/688,064

October 13, 2000

ALIGNING AN OPTICAL DEVICE SYSTEM WITH AN OPTICAL DEVICE SYSTEM

Examiner: Tran, Minni L.

CENTRAL DEVICE SYSTEM WITH AN OPTICAL DEVICE SYSTEM

CENTRAL DEVICE SYSTEM WITH AN OPTICAL DEVICE SYS

Commissioner for Patents Washington, D.C. 20231

## RESPONSE

In response to the Examiner's action dated May 10, 2002, please amend the application as follows. The amendments are presented below in clean form (i.e., without markings that indicate the changes that have been made); marked-up versions of the amendments are presented in the attached appendix.

# In the Drawings:

Please amend FIG. 6A as marked in red in the attached drawing sheet. A formal drawing sheet incorporating this amendment also is attached.

# In the Specification:

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Please replace the paragraph at page 7, lines 1-27, with the following paragraph:

-- Referring to FIG. 2, in one embodiment, optoelectronic device 10 includes an optical device system 40 having an optical device substrate 42 supporting an optical device 44 (e.g., a light detector, such as a p-i-n diode, or a light-emitter, such as a VCSEL) and a solderable metallization pattern 46, 48 having a spatial arrangement with respect to optical device 44. Optoelectronic device 10 also includes an optical lens system 50 having an optical element 52 and a device bonding surface 54 supporting a solderable metallization pattern 56, 58 with a spatial arrangement with respect to optical element 52. The metallization patterns

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